



TAPES USED IN THE MANUFACTURE OF SEMICONDUCTOR PACKAGES

RD-658Q

NEW

Polyester film with a low adhesion acrylic adhesive – specially developed as a silicone rubber encapsulant, it can be readily removed after encapsulant curing without damaging the polyimide lead frame or leaving adhesive residue.



SP-634

NEW

Polyimide film with a silicone adhesive
This version has been specifically developed for use with epoxy based encapsulents. These require higher curing temperatures in comparison to silicone encapsulents. Removable without damaging the lead frame or leaving adhesive residue.